TOSHIBA Field Effect Transistor Silicon N Channel MOS Type (π-MOSV)

# **TPCS8004**

High Speed Switching Applications Switching Regulator Applications DC-DC Converters

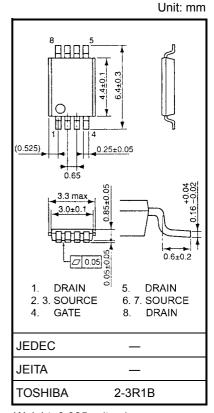
- Small footprint due to small and thin package
- Low drain-source ON resistance: RDS (ON) =  $0.56 \Omega$  (typ.)
- High forward transfer admittance:  $|Y_{fs}| = 1.8 \text{ S (typ.)}$
- Low leakage current:  $I_{DSS} = 100 \,\mu\text{A} \,(\text{max}) \,(V_{DS} = 200 \,\text{V})$
- Enhancement-model:  $V_{th} = 1.5 \sim 3.5 \text{ V (V}_{DS} = 10 \text{ V, I}_{D} = 1 \text{ mA)}$

#### Maximum Ratings (Ta = 25°C)

Characteristics		Symbol	Rating	Unit	
Drain-source voltage		$V_{DSS}$	200	V	
Drain-gate voltage ( $R_{GS} = 20 \text{ k}\Omega$ )		$V_{DGR}$	200	V	
Gate-source voltage		V <sub>GSS</sub>	±20	V	
Drain current	DC (Note 1)	I <sub>D</sub>	1.3	Α	
	Pulse (Note 1)	I <sub>DP</sub>	5.2	^	
Drain power dissipation (t = 10 s) (Note 2a)		$P_{D}$	1.5	W	
Drain power dissipation (t = 10 s) (Note 2b)		P <sub>D</sub>	0.6	VV	
Single pulse avalanche energy(Note3)		E <sub>AS</sub>	1.05	mJ	
Avalanche current		I <sub>AR</sub>	1.3	Α	
Repetitive avalanche energy (Note2a, Note 4)		E <sub>AR</sub>	0.15	mJ	
Channel temperature		T <sub>ch</sub>	150	°C	
Storage temperature range		T <sub>stg</sub>	-55~150	°C	

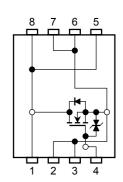
Note: For (Note 1), (Note 2), (Note 3) and (Note 4), please refer to the next page.

This transistor is an electrostatic sensitive device. Please handle with caution.



Weight: 0.035 g (typ.)

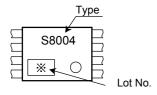
### **Circuit Configuration**



#### **Thermal Characteristics**

Characteristics	Symbol	Max	Unit
Thermal resistance, channel to ambient (t = 10 s) (Note 2a)	R <sub>th (ch-a)</sub>	83.3	°C/W
Thermal resistance, channel to ambient (t = 10 s) (Note 2b)	R <sub>th (ch-a)</sub>	208	°C/W

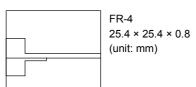
### Marking (Note 5)



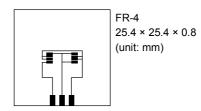
Note 1: Please use devices on condition that the channel temperature is below 150°C.

Note 2:

a) Device mounted on a glass-epoxy board (a)



b) Device mounted on a glass-epoxy board (b)



Note 3:  $V_{DD}$  = 50 V,  $T_{ch}$  = 25°C (initial), L = 1.0 mH,  $R_G$  = 25  $\Omega$ ,  $I_{AR}$  = 1.3 A

Note 4: Repetitive rating: pulse width limited by maximum channel temperature

Note 5: O on lower right of the marking indicates Pin 1.

Weekly code: (Three digits)
 Week of manufacture
 (01 for first week of year, continues up to 52 or 53)
 Year of manufacture
 (One low-order digits of calendar year)

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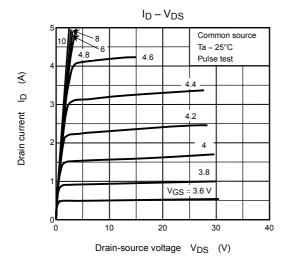
# Electrical Characteristics (Ta = 25°C)

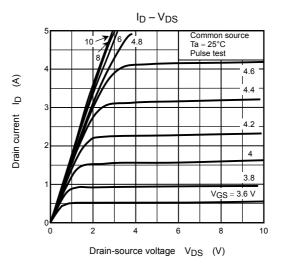
Cha	aracteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Gate leakage current		I <sub>GSS</sub>	$V_{GS} = \pm 16 \text{ V}, V_{DS} = 0 \text{ V}$	_	_	±10	μΑ
Drain cut-OFF current		I <sub>DSS</sub>	V <sub>DS</sub> = 200 V, V <sub>GS</sub> = 0 V		_	100	μΑ
Drain-source breakdown voltage		V <sub>(BR) DSS</sub>	$I_D = 10 \text{ mA}, V_{GS} = 0 \text{ V}$	200	_	_	٧
Gate threshold voltage		V <sub>th</sub>	$V_{DS} = 10 \text{ V}, I_{D} = 1 \text{ mA}$	1.5	_	3.5	٧
Drain-source ON resistance		R <sub>DS (ON)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 0.6 A		0.56	0.8	Ω
Forward transfer	admittance	Y <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 0.6 A	0.9	1.8		S
Input capacitance	1	C <sub>iss</sub>			380		pF
Reverse transfer capacitance		C <sub>rss</sub>	V <sub>DS</sub> = 10 V, V <sub>GS</sub> = 0 V, f = 1 MHz		40		pF
Output capacitance		C <sub>oss</sub>			140		pF
Switching time	Rise time	t <sub>r</sub>	$V_{GS} \stackrel{10}{\underset{O}{\text{V}}} \bigvee \stackrel{I_{D}}{\underset{O}{\text{V}}} = 0.6 \text{ A}$ $V_{DD} \approx 100 \text{ V}$ $V_{DD} \approx 100 \text{ V}$ $V_{DD} \approx 100 \text{ µs}$	_	4.5	_	
	Turn-ON time	t <sub>on</sub>		_	12		20
	Fall time	t <sub>f</sub>			23	_	ns
	Turn-OFF time	t <sub>off</sub>		_	54		
Total gate charge (gate-source plus gate-drain)		Qg	$V_{DD} \simeq 160 \text{ V}, V_{GS} = 10 \text{ V},$ $I_D = 1.3 \text{ A}$		12		nC
Gate-source charge		Q <sub>gs</sub>			8	_	nC
Gate-drain ("miller") charge		Q <sub>gd</sub>		_	4	_	nC

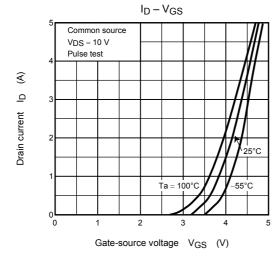
## **Source-Drain Ratings and Characteristics (Ta = 25°C)**

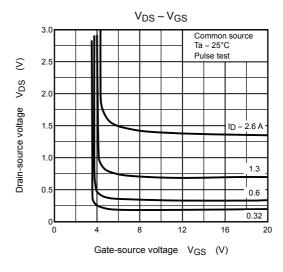
Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit
Drain reverse current (pulse) (Note 1)	I <sub>DRP</sub>	_	_	_	5.2	Α
Forward voltage (diode)	V <sub>DSF</sub>	$I_{DR} = 1.3 \text{ A}, V_{GS} = 0 \text{ V}$	_	_	-2.0	V
Reverse recovery time	t <sub>rr</sub>	$I_{DR} = 1.3 \text{ A}, V_{GS} = 0 \text{ V},$	_	89	_	ns
Reverse recovery charge	Q <sub>rr</sub>	dI <sub>DR</sub> /dt = 100 A/μs	_	230	_	nC

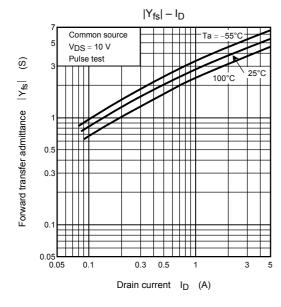
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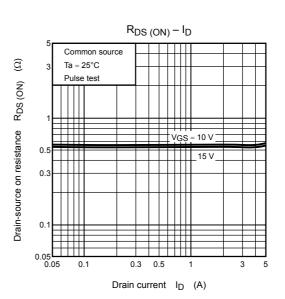


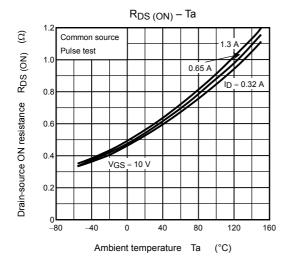


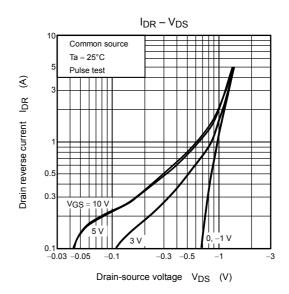


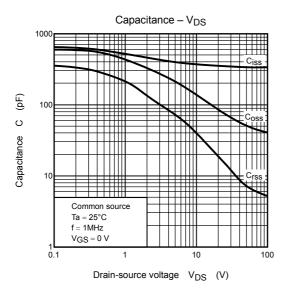


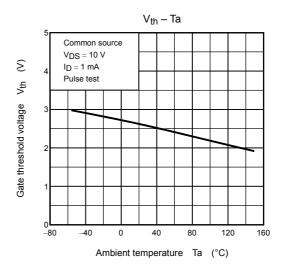


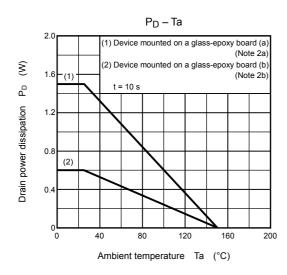


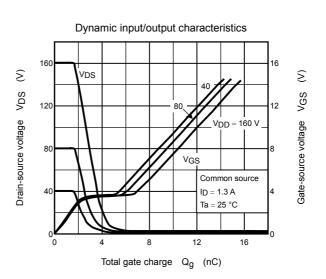


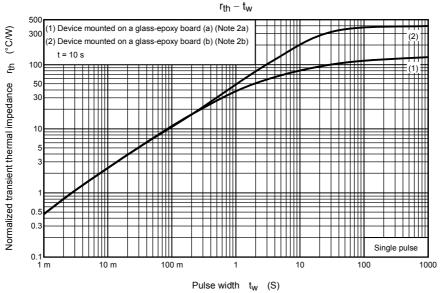


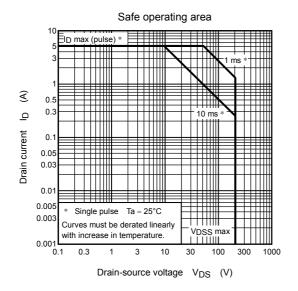


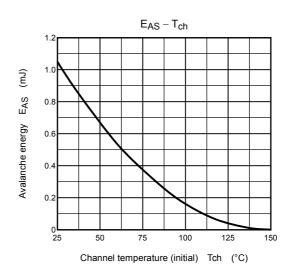


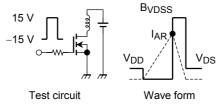












$$\begin{split} &T_{Ch}=25^{\circ}C\text{ (Initial)}\\ &\text{Peak I}_{AR}=1.3\text{ A, R}_{G}=25\text{ }\Omega \quad \text{E}_{AS}=\frac{1}{2}\cdot\text{L}\cdot\text{I}^{2}\cdot\left(\frac{\text{B}_{VDSS}}{\text{B}_{VDSS}-\text{V}_{DD}}\right) \\ &\text{V}_{DD}=50\text{ V, L}=1\text{ mH} \end{split}$$

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